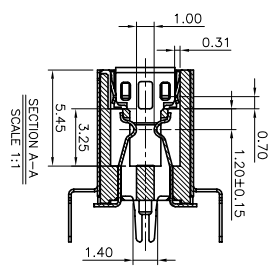
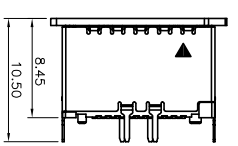
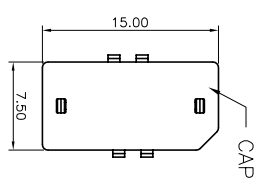
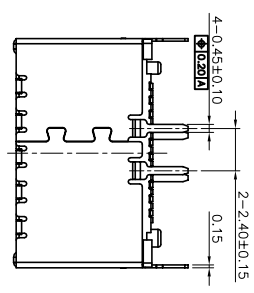
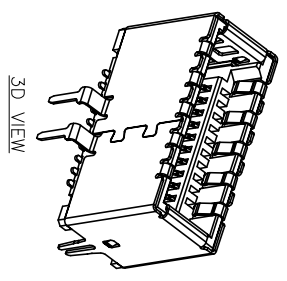
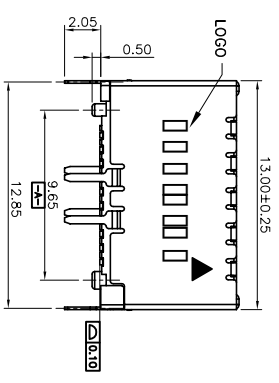
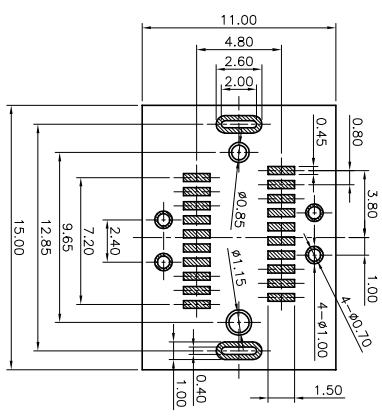
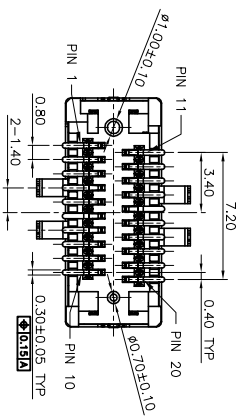
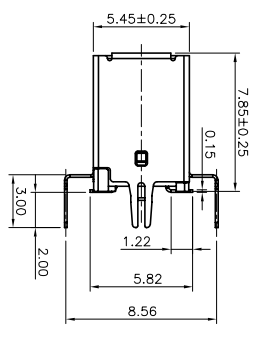
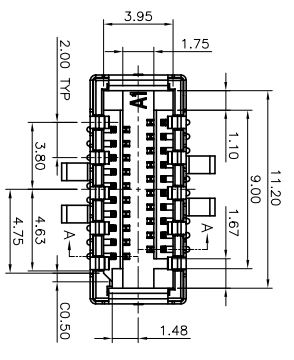


REV.	ECH. NO.	APPD.
A	/	/



NOTES:  
 说明  
 1. EMI SHELL SOLDER LEAD IS CONNECTED TO THE ADJACENT GND PIN VIA TRACE. IT NEED TO BE ISOLATED BY SOLDER RESIST.  
 如果电磁干扰外壳引线连接到邻接的接地引脚上, 需要打阻焊剂隔离。



TOLERANCE UNLESS OTHERWISE SPECIFIED		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.,LTD.	
.XXX ±0.10	X' ±3'	<b>HLW</b> 深圳市华联威电子科技有限公司 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.,LTD.	
.XX ±0.20	.XX ±2'		
.X ±0.30	.XX ±2'		
APPROVED	PART NAME:	USB 3.1TYPE E KEYAZOPIN脚板式	
CHECKED	PART NO.:	U573-089B-161038	
DRAWN	PROJECTION:	UNIT:	SCALE
DATE	2021.07.23	mm	1:1

A	B	C	D	E	F	9	8	7	6	5	4	3	2	1
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